

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of )  
 )  
Takayama et al. )  
 )  
Serial No.: 09/598,736 )  
 )  
Filed: June 21, 2000 )  
 )  
For: Wiring Material, Semiconductor Device )  
Provided With A Wiring Using The Wiring )  
Material And Method Of Manufacturing )  
Thereof )  
 )  
Art Unit: 2811 )  
 )  
Confirmation No.: 5820 )  
 )  
Examiner: Hung K. Vu )

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE H (AFTER FINAL)**

Sir:

Applicants have the following response to the Final Rejection of October 10, 2006.

Applicants appreciate the Examiner's allowance of Claims 28-39.

Applicants will now address the Examiner's remaining rejections in the order in which they appear in the Final Rejection.

**Claim Rejections - 35 USC §102**

In the Final Rejection, the Examiner rejects Claims 1, 5 and 115 under 35 USC §102(b) as being anticipated by Oikawa et al. (US 4,770,948). This rejection is respectfully traversed.